#### **AP15P06S Description**

The AP15P06S uses advanced trench technology to provide excellent  $R_{\text{DS}(\text{ON})}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **AP15P06S General Features**

 $V_{DS} = -60V I_{D} = -15A$ 

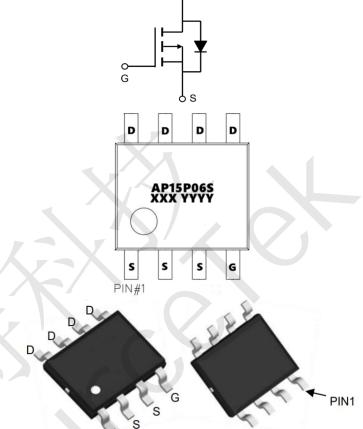
 $R_{DS(ON)} < 28m\Omega$  @  $V_{GS}=-10V$  (Type: 20m $\Omega$ )

#### **AP15P06S Application**

**BMS** 

Low voltage switch

Electric tool



## AP15P06S Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15P06S	SOP-8L	AP15P06S XXX YYYY	3000

#### AP15P06S Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	-60	V	
VGS	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	T <sub>C</sub> =25°C Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup> -15		А	
ID@Tc=100°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-8.5	А	
IDM	Pulsed Drain Current <sup>2</sup>	-45	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	113	mJ	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	52.1	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	℃	
ReJA	Thermal Resistance Junction-Ambient <sup>1</sup> 85 °C		°C/W	
R <sub>θ</sub> JC	Thermal Resistance Junction-Case <sup>1</sup> 2.4		°C/W	

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### AP15P06S Electrical Characteristics (T<sub>c</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-60	-68		V	
△BVDSS/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =-1mA		-0.035		V/°C	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-12A		20	28	mΩ	
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-8A		26	33	11122	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID250uA		4.28		mV/℃	
IDSS	Drain Source Leakage Current	V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA	
1033	Drain-Source Leakage Current	$V_{DS}$ =-48V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C	-		5		
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-18A		23		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	/	7		Ω	
Qg	Total Gate Charge (-4.5V)	/ X		25			
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =-20V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-12A		6.7		nC	
$Q_{gd}$	Gate-Drain Charge	IZA		5.5			
Td(on)	Turn-On Delay Time		/	38			
Tr	Rise Time	$V_{DD}$ =-15V , $V_{GS}$ =-10V , $R_{G}$ =3.3 $\Omega$ ,		23.6			
Td(off)	Turn-Off Delay Time	I <sub>D</sub> =-1A	4	100		ns	
Tf	Fall Time	ID-1A		6.8			
Ciss	Input Capacitance			3635			
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		224		рF	
Crss	Reverse Transfer Capacitance			141			
Is	Continuous Source Current <sup>1,5</sup>				-35	Α	
ISM	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-70	Α	
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1	V	

#### Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3、The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

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## **AP15P06S Typical Characteristics**

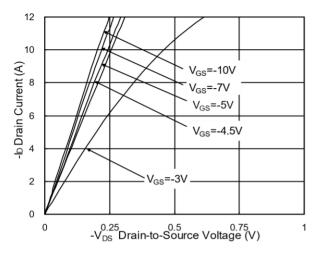


Fig.1 Typical Output Characteristics

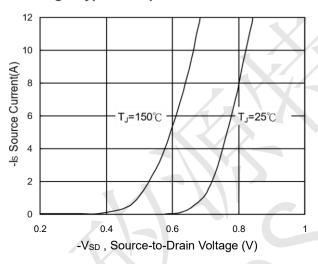


Fig.3 Forward Characteristics Of Reverse

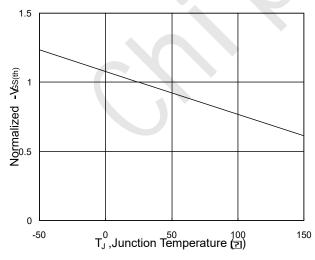


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$ 

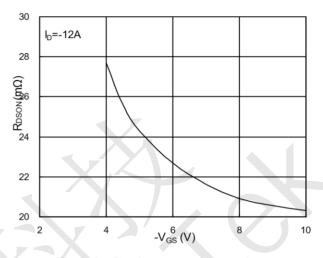


Fig.2 On-Resistance v.s Gate-Source

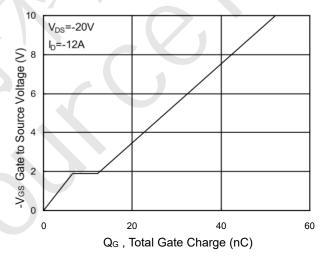


Fig.4 Gate-Charge Characteristics

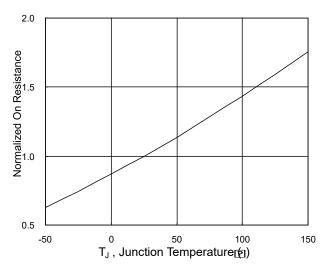
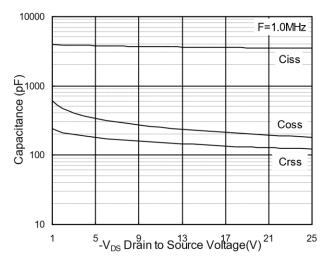


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



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# -60V P-Channel Enhancement Mode MOSFET AP15P06S



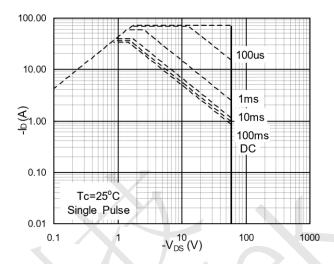
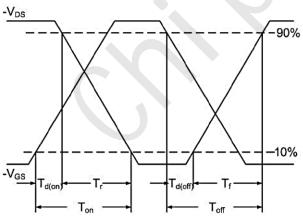


Fig.8 Safe Operating Area Fig.7 Capacitance Normalized Thermal Response (Reuc) DUTY=0.5 0.3 0.1 0.05 0.02 = 0.01  $D = T_{ON}/T$ SINGLE PULSE  $T_Jpeak = T_C + P_{DM} x R_{\theta JC}$ 0.01 0.00001 0.0001 t, Pulse Width (s)

Fig.9 Normalized Maximum Transient Thermal Impedance





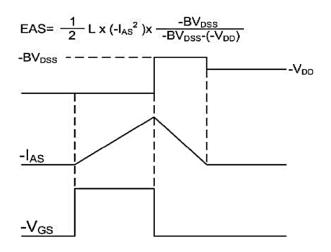
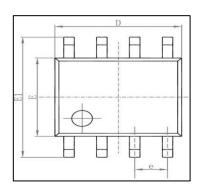
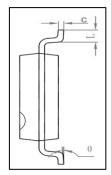
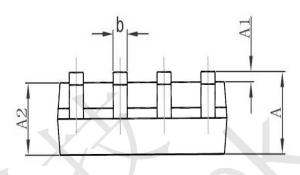


Fig.11 Unclamped Inductive Waveform

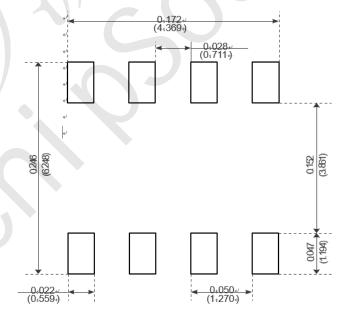
## AP15P06S Package Mechanical Data-SOP-8L







C	Dimensions I	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1. 350	1. 750	0. 053	0. 069
A1	0. 100	0. 250	0. 004	0.010
A2	1. 350	1. 550	0. 053	0. 061
b	0. 330	0. 510	0. 013	0. 020
С	0. 170	0. 250	0.006	0. 010
D	4. 700	5. 100	0. 185	0. 200
E	3.800	4. 000	0. 150	0. 157
E1	5. 800	6. 200	0. 228	0. 244
е	1. 270	(BSC)	0.050	(BSC)
L	0. 400	1. 270	0. 016	0. 050
θ	0°	8°	0°	8°



Recommended Minimum Pads



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Edition	Date	Change
Rve1.0	2022/1/31	Initial release

